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(54) Title of the Device: Printed wiring board

(57) Claims

A printed wiring board having an aperture-like adhesive application point, piercing a resist layer and reaching a substrate, which is formed in resist applied between conductors in order to secure a passive element component on the substrate by soldering, in accordance with the position of the component.

Brief Description of the Drawings

Fig. 1 is a front sectional view of a conventional printed wiring board with a component mounted thereon. Fig. 2 is a front sectional view showing a dropped state of adhesive in a conventional example. Fig. 3 is a front sectional view of a printed wiring board with a component mounted thereon in an embodiment of the present utility model. Fig. 4 is a front sectional view showing a dropped state of adhesive in the present utility model.

The reference numerals mentioned in the drawings are as follows.

1 Substrate

2 Conductor